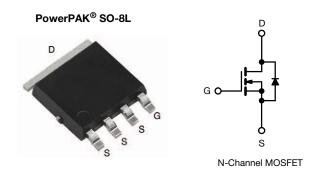
**HALOGEN** FREE



# **E Series Power MOSFET**

PRODUCT SUMMARY				
V <sub>DS</sub> (V) at T <sub>J</sub> max.	700			
R <sub>DS(on)</sub> typ. (Ω) at 25 °C	V <sub>GS</sub> = 10 V 0.755			
Q <sub>g</sub> max. (nC)	32			
Q <sub>gs</sub> (nC)	5			
Q <sub>gd</sub> (nC)	7			
Configuration	Single			



#### **FEATURES**

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- · Reduced switching and conduction losses
- Ultra low gate charge (Q<sub>a</sub>)
- Avalanche energy rated (UIS)
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

### **APPLICATIONS**

- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
  - High-intensity discharge (HID)
  - Fluorescent ballast lighting
- Consumer
  - Adaptors

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and Halogen-free	SiHJ6N65E-T1-GE3

ABSOLUTE MAXIMUM RATINGS (	Γ <sub>C</sub> = 25 °C, unl	ess otherwis	se noted)		
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			$V_{DS}$	650	V
Gate-Source Voltage			$V_{GS}$	± 30	7 v
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C		5.6	A
Continuous Drain Current (1) = 150 C)	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C		3.6	
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	12	
Linear Derating Factor				0.76	W/°C
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	36	mJ
Maximum Power Dissipation			$P_{D}$	74	W
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-Source Voltage Slope T <sub>J</sub> = 125 °C			dV/dt	70	V/ns
Reverse Diode dV/dt <sup>c</sup>				9.4	V/115

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b.  $V_{DD} = 120 \text{ V}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ ,  $L = 28.2 \,\text{mH}$ ,  $R_q = 25 \,\Omega$ ,  $I_{AS} = 1.6 \,\text{A}$ .
- c.  $I_{SD} \le I_D$ ,  $dI/dt = 100 \text{ A/}\mu\text{s}$ , starting  $T_J = 25 \,^{\circ}\text{C}$ .

THERMAL RESISTANCE RATINGS					
PARAMETER SYMBOL TYP. MAX. UNIT					
Maximum Junction-to-Ambient	R <sub>thJA</sub>	52	65	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	1.2	1.7	G/VV	

Vishay Siliconix

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static					•		
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		650	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.8	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
Cata Caurea Laglaga		,	$V_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
Gate-Source Leakage	I <sub>GSS</sub>	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zara Cata Valtaga Drain Current		V <sub>DS</sub> =	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 520 V	, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	$I_D = 3 A$	-	0.755	0.868	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 30 V, I <sub>D</sub> = 3 A	-	1.8	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V,	-	596	-	
Output Capacitance	C <sub>oss</sub>	Ī ,	$V_{\rm DS} = 100 \text{ V},$	-	35	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		f = 1 MHz	-	4	-	
Effective Output Capacitance, Energy Related <sup>a</sup>	C <sub>o(er)</sub>	V <sub>DS</sub> = 0 V to 520 V, V <sub>GS</sub> = 0 V		-	26	-	pF
Effective Output Capacitance, Time Related <sup>b</sup>	C <sub>o(tr)</sub>			-	90	-	
Total Gate Charge	Qg			-	16	32	
Gate-Source Charge	Q <sub>gs</sub>	$V_{GS} = 10 \text{ V}$ $I_D = 3 \text{ A}, V_{DS} = 520 \text{ V}$		-	5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>			-	7	-	
Turn-On Delay Time	t <sub>d(on)</sub>			-	14	28	
Rise Time	t <sub>r</sub>	V <sub>DD</sub> = 520 V, I <sub>D</sub> = 3 A,		-	14	28	
Turn-Off Delay Time	t <sub>d(off)</sub>	V <sub>GS</sub> =	$= 10 \text{ V}, \text{ R}_{\text{g}} = 9.1 \Omega$	-	25	50	ns ns
Fall Time	t <sub>f</sub>			-	17	34	
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz		0.4	0.8	1.6	Ω
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET sym showing the	bol	-	-	5.6	
Pulsed Diode Forward Current	I <sub>SM</sub>	integral reverse p - n junction diode		-	-	12	- A
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 3 A, V <sub>GS</sub> = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>			-	278	556	ns
Reverse Recovery Charge	Q <sub>rr</sub>	$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 3 \text{A},$ $dI/dt = 100 \text{A/µs}, V_R = 25 \text{V}$		_	2.1	4.2	μC
Reverse Recovery Current	I <sub>RRM</sub>	ai/at =	100 A/μS <sup>, *</sup> R = 25 V	_	12	_	Α

a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ . b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$ .



### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

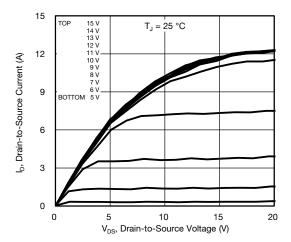


Fig. 1 - Typical Output Characteristics

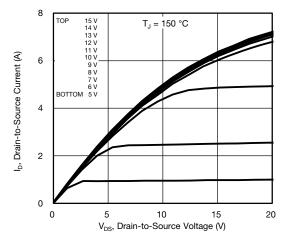


Fig. 2 - Typical Output Characteristics

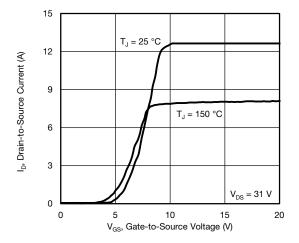


Fig. 3 - Typical Transfer Characteristics

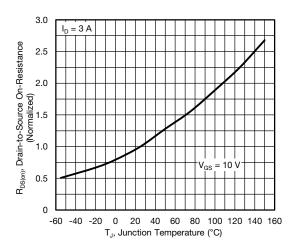


Fig. 4 - Normalized On-Resistance vs. Temperature

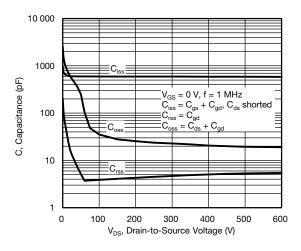


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

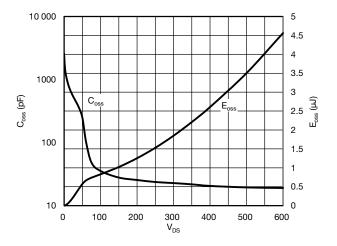


Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$ 



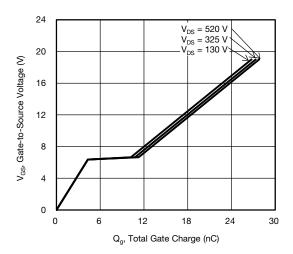


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

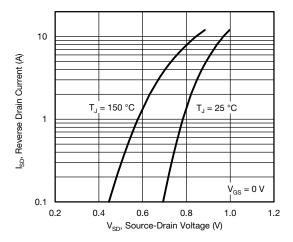


Fig. 8 - Typical Source-Drain Diode Forward Voltage

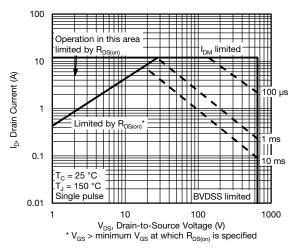


Fig. 9 - Maximum Safe Operating Area

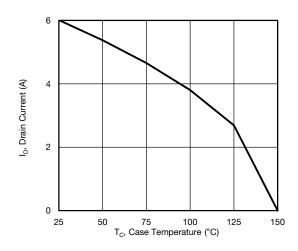


Fig. 10 - Maximum Drain Current vs. Case Temperature

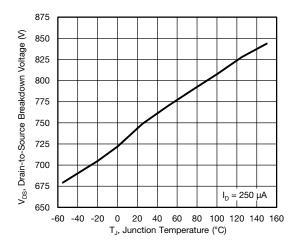


Fig. 11 - Temperature vs. Drain-to-Source Voltage



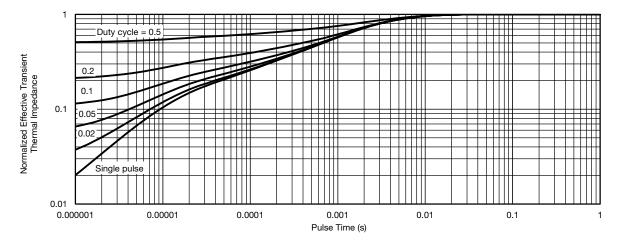


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

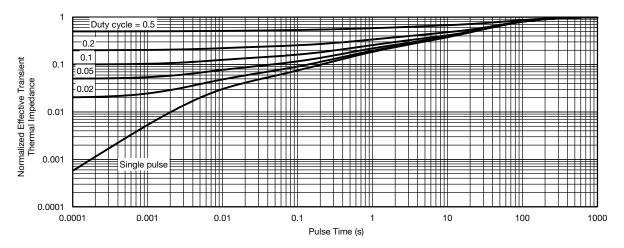


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

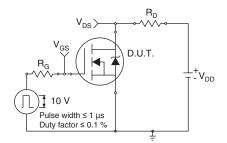


Fig. 14 - Switching Time Test Circuit

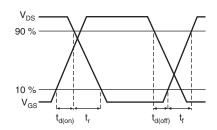


Fig. 15 - Switching Time Waveforms



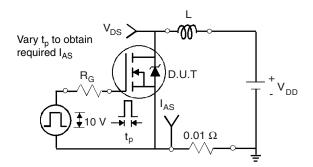


Fig. 16 - Unclamped Inductive Test Circuit

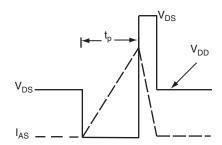


Fig. 17 - Unclamped Inductive Waveforms

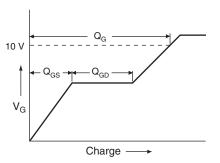


Fig. 18 - Basic Gate Charge Waveform

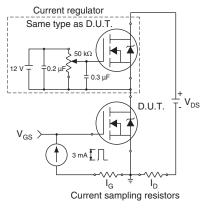
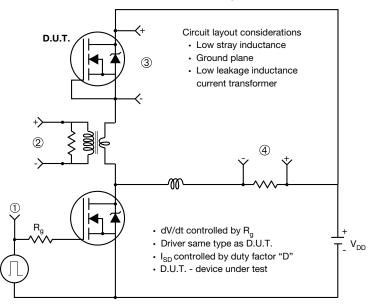


Fig. 19 - Gate Charge Test Circuit



#### Peak Diode Recovery dV/dt Test Circuit



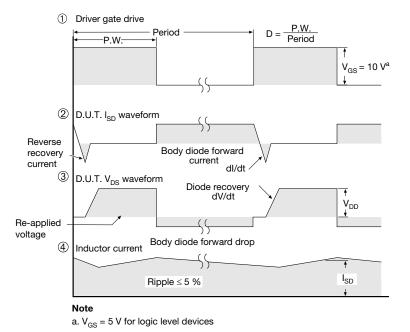
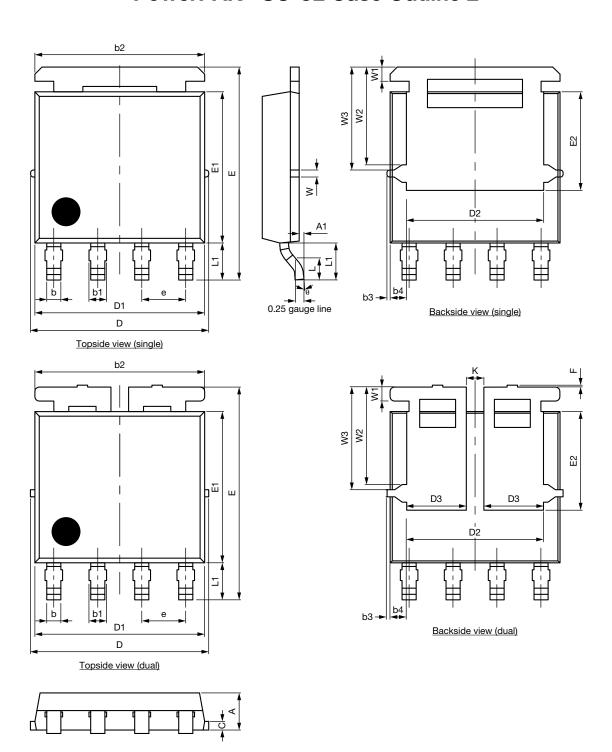


Fig. 20 - For N-Channel

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# PowerPAK® SO-8L Case Outline 2



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DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094	_		0.004	•	
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51	•	0.020			
W	0.23		0.009				
W1	0.41		0.016				
W2	2.82		0.111				
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

ECN: C21-1498-Rev. C, 01-Nov-2021

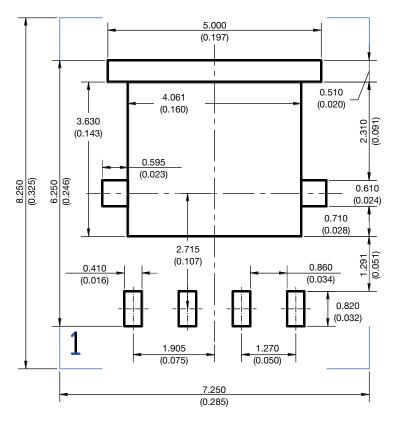
DWG: 6044

#### Note

• Millimeters will govern



#### RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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